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Silicon NPN Epitaxial Planar

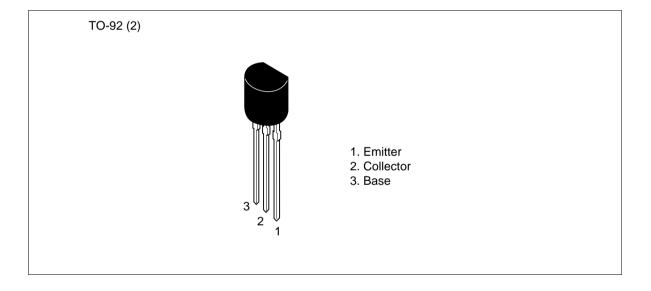


ADE-208-1058 (Z) 1st. Edition Mar. 2001

Application

- VHF amplifier
- Mixer, Local oscillator

Outline



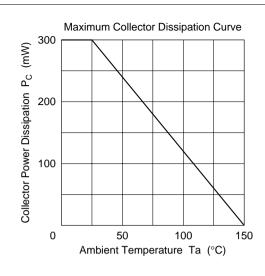
Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

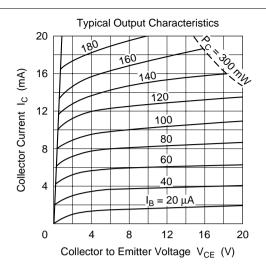
Item	Symbol	Ratings	Unit	
Collector to base voltage	V_{CBO}	30	V	
Collector to emitter voltage	V_{CEO}	19	V	
Emitter to base voltage	V_{EBO}	2	V	
Collector current	I _c	50	mA	
Emitter current	I _E	- 50	mA	
Collector power dissipation	P _c	300	mW	
Junction temperature	Tj	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

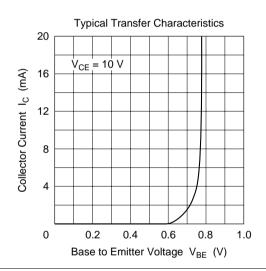
Electrical Characteristics ($Ta = 25^{\circ}C$)

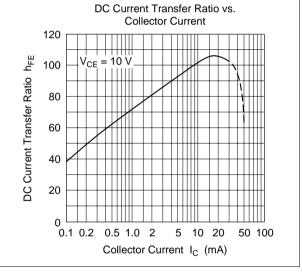
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	30	_	_	V	$I_{c} = 10 \ \mu\text{A}, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	19	_	_	V	$I_C = 3 \text{ mA}, R_{BE} =$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	2	_	_	V	$I_{E} = 10 \mu A, I_{C} = 0$
Collector cutoff current	I _{CBO}	_	_	0.5	μΑ	$V_{CB} = 10 \text{ V}, I_{E} = 0$
DC current transfer ratio	h _{FE}	40	_	_		$V_{CE} = 10 \text{ V}, I_{C} = 10 \text{ mA}$
Gain bandwidth product	f _T	600	1000	_	MHz	$V_{CE} = 10 \text{ V}, I_{C} = 10 \text{ mA}$
Collector output capacitance	Cob	_	1.0	2.0	pF	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	0.2	1.0	V	$I_C = 20 \text{ mA}, I_B = 4 \text{ mA}$
Base time constant	r _{bb′} ⋅C _C	_	10	25	ps	$V_{CB} = 10 \text{ V}, I_{C} = 10 \text{ mA},$ f = 31.8 MHz
Power gain	PG	_	33	_	dB	$V_{CE} = 10 \text{ V}, \qquad f = 45 \text{ MHz}$ $I_{C} = 5 \text{ mA}$
		_	18		dB	$V_{CE} = 10 \text{ V}, \qquad f = 200 \text{ MHz}$ $I_C = 5 \text{ mA}$



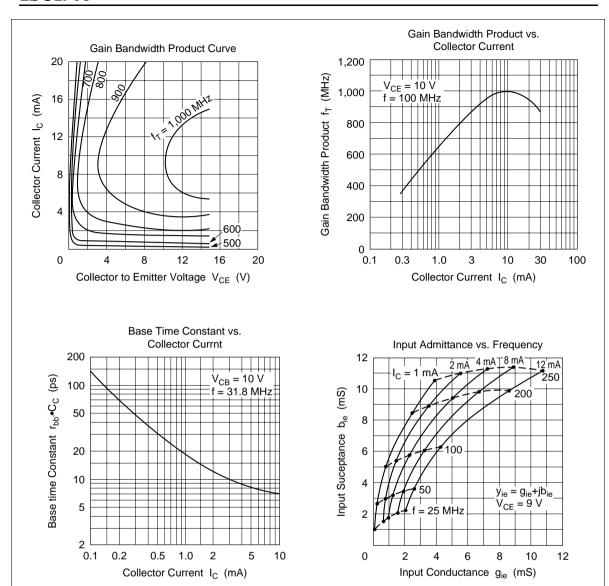


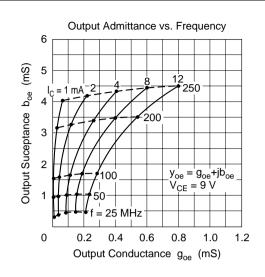


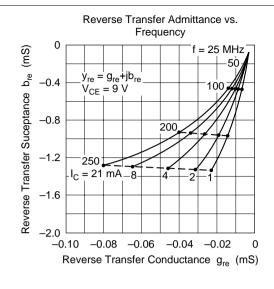


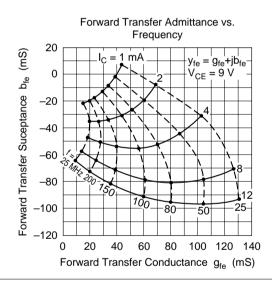


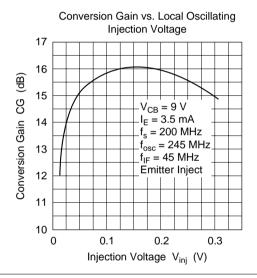
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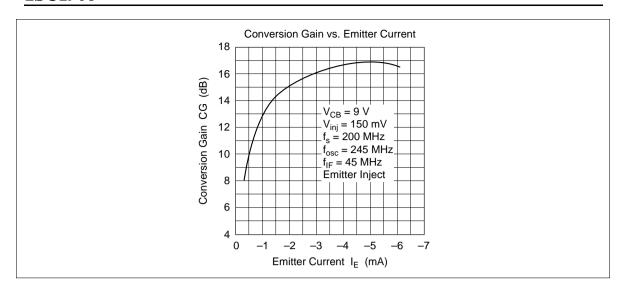




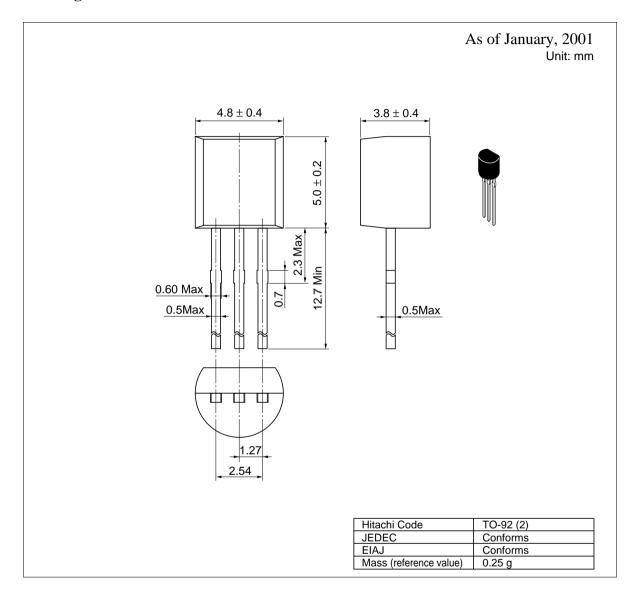








Package Dimensions



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